

IN THE CLAIMS

1 (Currently Amended). A display comprising:

a plurality of substrates, each substrate having a recess;

a plurality of display elements formed on each substrate;

an integrated circuit block mounted in the recess on each substrate at an intersection between four and coupled to at least one of said display elements and said block coupled to each of said four display elements; and

an integrator to couple said substrates to form a tiled display.

2 (Original). The display of claim 1 wherein said display element is a light emitting diode.

3 (Original). The display of claim 2 wherein said element is an organic light emitting diode.

4 (Original). The display of claim 1 wherein said integrated circuit block is a complementary metal oxide semiconductor integrated circuit.

Claim 5 (Canceled).

6 (Previously Presented). The display of claim 1 wherein each block and said substrate are complementarily shaped.

7 (Original). The display of claim 1 wherein said block is a driver circuit for said display element.

8 (Original). The display of claim 7 wherein said block is located between a plurality of display elements.

9 (Original). The display of claim 1 wherein said block is metallized with said substrate.

10 (Original). The display of claim 1 including a ceramic back plane and a front plane including said block.

11 (Original). The display of claim 1 wherein said block is formed of a silicon substrate and said substrate is formed of glass.

12 (Currently Amended). A display comprising:

a back plane;

an optical integrator; and

a front plane between said back plane and said optical integrator, said front plane including four a plurality of adjacent, intersecting emissive display elements formed on said front plane and an integrated circuit block secured in said front plane between said display elements, said block and including a driver circuit circuits coupled to each of said display elements and to said back plane.

13 (Original). The display of claim 12 wherein said display elements are light emitting diodes.

14 (Original). The display of claim 13 wherein said elements are organic light emitting diodes.

15 (Original). The display of claim 12 wherein said block is formed of a metal oxide semiconductor integrated circuit and said front plane is formed of glass.

16 (Original). The display of claim 12 wherein said block is deposited in a recess formed in said front plane.

17 (Original). The display of claim 12 wherein said driver circuit drives a plurality of adjacent display elements.

18 (Currently Amended). A method comprising:

forming a plurality of light emitting display elements on a module;

forming recesses in said module to receive integrated circuit nanoblocks with each recess formed between four adjacent intersecting display elements;

depositing said nanoblocks in said recesses;

electrically coupling each said nanoblock nanoblocks to said four display elements; and

connecting a plurality of modules to form a tiled display.

19 (Original). The method of claim 18 including etching a recess in said module to receive said integrated circuit nanoblock.

20 (Original). The method of claim 18 including forming a plurality of nanoblocks by forming a sacrificial layer on a silicon substrate, etching said substrate and then finally etching said sacrificial layer.

21 (Original). The method of claim 18 including coupling said nanoblocks to circuits behind said light emitting display.

22 (Original). The method of claim 18 including coupling said nanoblocks to said circuits through bond pads on said nanoblocks.

23 (Previously Presented). The display of claim 1 wherein said block is a nanoblock.

24 (Previously Presented). The display of claim 23 wherein said nanoblock includes an upper surface exposed when said block is mounted in said recess, said upper surface being substantially coplanar with said substrate.

25 (New). The display of claim 1 wherein said recess is formed at the juncture of said four display elements such that a part of said recess is formed in each of said four display elements and said block is positioned at the intersection of said four display elements.

26 (New). The display of claim 12 wherein said integrated circuit block is secured over the intersection of said four display elements.

27 (New). The method of claim 18 including forming a recess at the intersection between four adjacent display elements and depositing a nanoblock in said recess so that said block overlaps all four of said display elements.